Quad Line Receiver

Description

The MC10H115 is a quad differential amplifier designed for use in sensing differential signals over long lines. This 10H part is a functional/ pinout duplication of the standard MECL $10K^{\text{TM}}$ family part, with 100% improvement in counting frequency and no increase in power supply current.

The base bias supply (V_{BB}) is made available at Pin 9 to make the device useful as a Schmitt trigger, or in other applications where a stable reference voltage is necessary. Active current sources provide the MC10H115 with excellent common mode rejection. If any amplifier in a package is not used, one input of that amplifier must be connected to V_{BB} (Pin 9) to prevent upsetting the current source bias network.

The MC10H115 is designed to be used in sensing differential signals over long lines. The bias supply (V_{BB}) is made available to make the device useful as a Schmitt trigger, or in other applications where a stable reference voltage is necessary.

Active current sources provide these receivers with excellent common–mode noise rejection. If any amplifier in a package is not used, one input of that amplifier must be connected to V_{BB} to prevent unbalancing the current source bias network.

The MC10H115 does not have internal input pulldown resistors. This provides high impedance to the amplifier input and facilitates differential connections.

Features

- Propagation Delay, 1.0 ns Typical
- Power Dissipation 110 mW Typ/Pkg (No Load)
- Improved Noise Margin 150 mV (Over Operating Voltage and Temperature Range)
- Voltage Compensated
- MECL 10K Compatible

Applications

- Low Level Receiver
- Voltage Level Interface
- Schmitt Trigger
- Pb-Free Packages are Available*



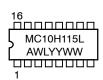
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MARKING DIAGRAMS*









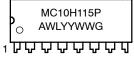
PDIP-16 P SUFFIX CASE 648

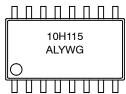


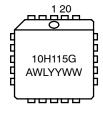
SOEIAJ-16 CASE 966



PLLC-20 FN SUFFIX CASE 775







A = Assembly Location
WI I = Wafer Lot

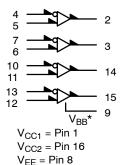
WL, L = Wafer Lot YY, Y = Year WW, W = Work Week G = Pb-Free Package

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

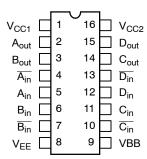
^{*}For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

^{*}For additional marking information, refer to Application Note AND8002/D.



 $^*V_{BB}$ to be used to supply bias to the MC10H115 only and bypassed (when used) with 0.01 μF to 0.1 μF capacitor to ground (0 V). V_{BB} can source < 1.0 mA. When input pin with bubble goes positive its respective

When input pin with bubble goes positive its output pin with bubble goes positive.



Pin assignment is for Dual-in-Line Package.

Figure 2. Pin Assignment

Figure 1. Logic Diagram

Table 1. MAXIMUM RATINGS

Symbol	Characteristic		Rating	Unit
V _{EE}	Power Supply (V _{CC} = 0)		-8.0 to 0	Vdc
VI	Input Voltage (V _{CC} = 0)		0 to V _{EE}	Vdc
l _{out}	Output Current	Continuous Surge	50 100	mA
T _A	Operating Temperature Range		0 to +75	°C
T _{stg}	Storage Temperature Range	Plastic Ceramic	−55 to +150 −55 to +165	°C

Maximum ratings are those values beyond which device damage can occur. Maximum ratings applied to the device are individual stress limit values (not normal operating conditions) and are not valid simultaneously. If these limits are exceeded, device functional operation is not implied, damage may occur and reliability may be affected.

Table 2. ELECTRICAL CHARACTERISTICS (V_{EE} = -5.2 V \pm 5%) (Note 2)

		C) °	25	5°	7	75°	
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
IE	Power Supply Current	-	29	_	26	_	29	mA
I _{inH}	Input Current High	-	150	-	95	-	95	μΑ
I _{CBO}	Input Leakage Current	-	1.5	_	1.0	_	1.0	μΑ
V_{BB}	Reference Voltage	-1.38	-1.27	-1.35	-1.25	-1.31	-1.19	Vdc
V _{OH}	High Output Voltage	-1.02	-0.84	-0.98	-0.81	-0.92	-0.735	Vdc
V _{OL}	Low Output Voltage	-1.95	-1.63	-1.95	-1.63	-1.95	-1.60	Vdc
V _{IH}	High Input Voltage (Note 1)	-1.17	-0.84	-1.13	-0.81	-1.07	-0.735	Vdc
V _{IL}	Low Input Voltage (Note 1)	-1.95	-1.48	-1.95	-1.48	-1.95	-1.45	Vdc
V _{CMR}	Common Mode Range (Note 3)	-	-	-2.85 t	to -0.8	-	-	Vdc
V_{PP}	Input Sensitivity (Note 4)	-	-	150	typ	_	-	mV_PP

^{1.} When V_{BB} is used as the reference voltage.

^{2.} Each MECL 10H™ series circuit has been designed to meet the specifications shown in the test table, after thermal equilibrium has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50 Ω resistor to −2.0 V.

^{3.} Differential input not to exceed 1.0 Vdc.

^{4. 150} mV_{p-p} differential input required to obtain full logic swing on output.

Table 3. AC PARAMETERS

		0 °		25°		75°		
Symbol	Characteristic	Min	Max	Min	Max	Min	Max	Unit
t _{pd}	Propagation Delay	0.4	1.3	0.4	1.3	0.45	1.45	ns
t _r	Rise Time	0.5	1.4	0.5	1.5	0.5	1.6	ns
t _f	Fall Time	0.5	1.4	0.5	1.5	0.5	1.6	ns

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

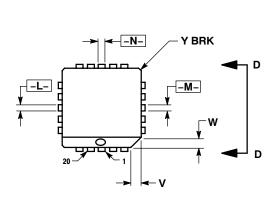
ORDERING INFORMATION

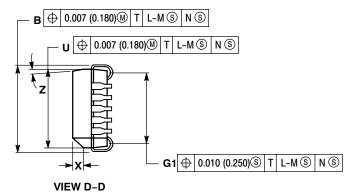
Device	Package	Shipping [†]
MC10H115FN	PLLC-20	46 Units / Rail
MC10H115FNG	PLLC-20 (Pb-Free)	46 Units / Rail
MC10H115FNR2	PLLC-20	500 / Tape & Reel
MC10H115FNR2G	PLLC-20 (Pb-Free)	500 / Tape & Reel
MC10H115L	CDIP-16	25 Unit / Rail
MC10H115M	SOEIAJ-16	50 Unit / Rail
MC10H115MG	SOEIAJ-16 (Pb-Free)	50 Unit / Rail
MC10H115MEL	SOEIAJ-16	2000 / Tape & Reel
MC10H115MELG	SOEIAJ-16 (Pb-Free)	2000 / Tape & Reel
MC10H115P	PDIP-16	25 Unit / Rail
MC10H115PG	PDIP-16 (Pb-Free)	25 Unit / Rail

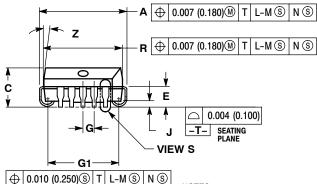
[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

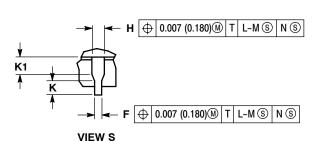
PACKAGE DIMENSIONS

20 LEAD PLLC CASE 775-02 **ISSUE E**









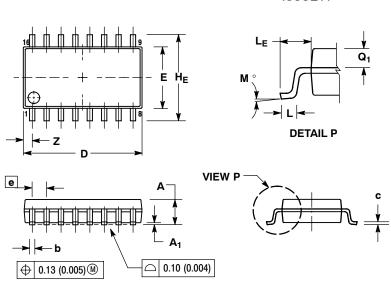
- NOTES:
 1. DIMENSIONS AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. DIMENSIONS IN INCHES.
 3. DATUMS -L., -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

- PARTING LINE.
 4. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM —T—, SEATING PLANE.
 5. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.
 6. DIMENSIONS IN THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY.
- PLASTIC BODY.
 7. DIMENSION H DOES NOT INCLUDE DAMBAR DIMIENSION HOUSEN OF INCLUDE DAMBAR
 PROTRUSION OR INTRUSION. THE DAMBAR
 PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION
 TO BE GREATER THAN 0.037 (0.940). THE DAMBAR
 INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO
 BE SMALLER THAN 0.025 (0.635).

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Е	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
Х	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

PACKAGE DIMENSIONS

SOEIAJ-16 CASE 966-01 **ISSUE A**



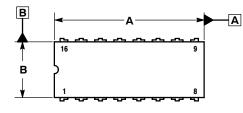
- NOTES:
 1. DIMENSIONING AND TOLERANCING PER ANSI

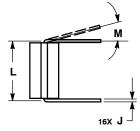
- NOTES:

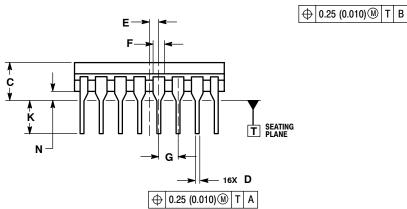
 1 DIMENSIONING AND TOLERANCING PER ANSI
 Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETER.
 3. DIMENSIONS DI AND E DO NOT INCLUDE MOLD
 FLASH OR PROTRUSIONS AND ARE MEASURED
 AT THE PARTING LINE. MOLD FLASH OR
 PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006)
 PER SIDE.
 4. TERMINAL NUMBERS ARE SHOWN FOR
 REFERENCE ONLY.
 5. THE LEAD WIDTH DIMENSION (b) DOES NOT
 INCLUDE DAMBAR PROTRUSION. ALLOWABLE
 DAMBAR PROTRUSION SHALL BE 0.08 (0.003)
 TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION.
 DAMBAR CANNOT BE LOCATED ON THE LOWER
 RADIUS OR THE FOOT. MINIMUM SPACE
 BETWEEN PROTRUSIONS AND ADJACENT LEAD
 TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A ₁	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
C	0.10	0.20	0.007	0.011
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	BSC	0.050 BSC	
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10 °	0 °	10°
Q ₁	0.70	0.90	0.028	0.035
Z		0.78		0.031

CDIP-16 **L SUFFIX** CERAMIC DIP PACKAGE CASE 620A-01 **ISSUE O**







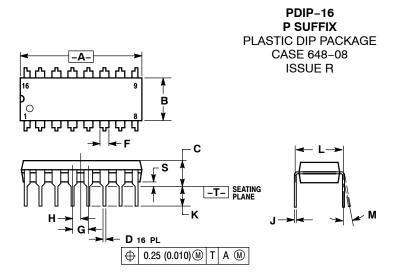
NOTES:

- DIMENSIONING AND TOLERANCING PER

- DIMENSIONING AND TOLEHARICING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: INCH.
 DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.
 DIMENSION F MAY NARROW TO 0.76 (0.030)
 WHERE THE LEAD ENTERS THE CERAMIC
- BODY.
 THIS DRAWING REPLACES OBSOLETE CASE OUTLINE 620-10.

	INCHES		MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
Е	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	0.100 BSC		BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	0.300 BSC		BSC	
M	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

PACKAGE DIMENSIONS



NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
- DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
 DIMENSION B DOES NOT INCLUDE MOLD FLASH.
 ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100	BSC	2.54 BSC		
Н	0.050	BSC	1.27 BSC		
J	0.008	0.015	0.21	0.38	
K	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
M	0°	10°	0°	10 °	
S	0.020	0.040	0.51	1.01	

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